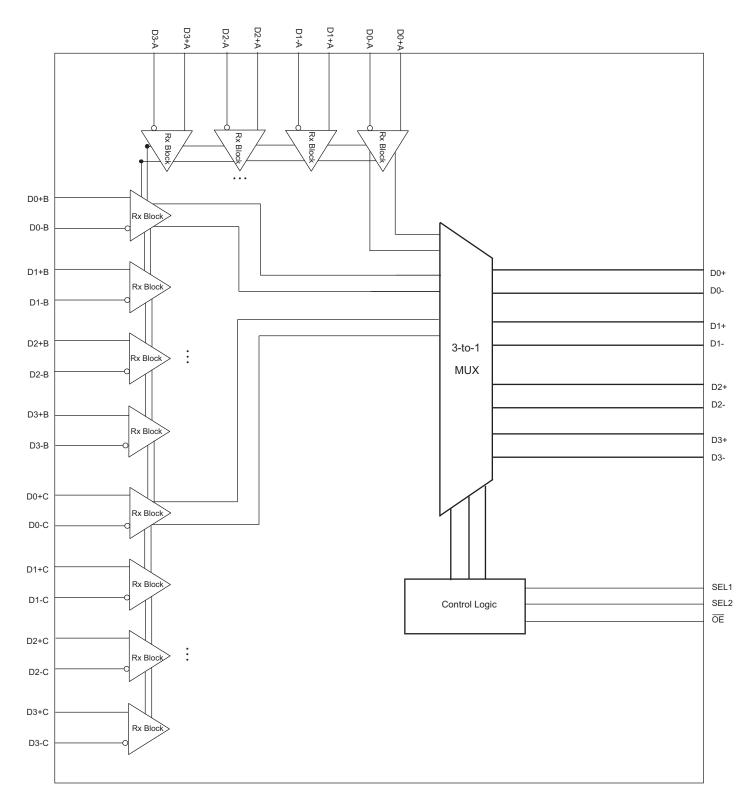


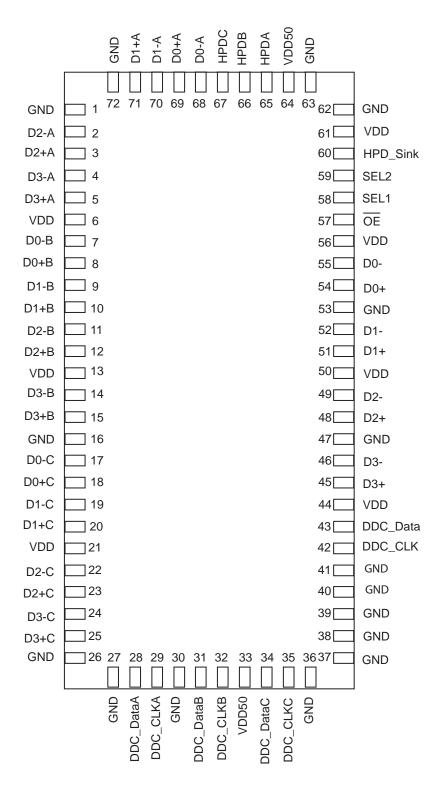
# High Speed Differential Signal Switch Block





## PI3HDMI1310-A HDMI<sup>™</sup> Switch with non-blocking EQ Circuitry

## **Pin Configuration** (Top View)





# **Pin Description**

Pin #	Pin Name	Pin Type	Description				
69, 68, 71, 70, 3, 2, 5, 4,	$Dx \pm A (X = 0, 1, 2, 3)$	I/O	Port A High Speed inputs				
8, 7, 10, 9, 12, 11, 15, 14	Dx $\pm$ B (X = 0, 1, 2, 3)	I/O	Port B High Speed inputs				
18, 17, 20, 19, 23, 22, 25, 24	Dx $\pm$ C (X = 0, 1, 2, 3)	I/O	Port C High Speed inputs				
65, 66, 67	HPDA, HPDB, HPDC	Output	truth table on pa	HPD open-drain outputs for each port. Logic will follow truth table on page 7. External 1Kohm pull-up to 5V is required			
33, 64	VDD50	Power	5.0V voltage rail standby-mode.	5.0V voltage rail from HDMI/DVI connector. Used during standby-mode.			
60	HPD_Sink	Input	GP I/O pin from SCALAR. Internal 100Kohm pull-down.				
29, 28, 32, 31, 35, 34, 42, 43	DDC_CLKx, DDC_Datax	I/O	I <sup>2</sup> C signals for DDC communication on TMDS ports				
55, 54, 53, 52, 51, 49, 48, 46, 45	$DX \pm (x = 0, 1, 2, 3)$	I/O	4-differential high speed Output signals				
			SEL1	SEL2	Output Port		
			0	0	Port A		
58, 59	SEL1, SEL2	Inputs	0	1	Port B		
			1	0	Port C		
			1	1	Hi-Z		
6, 13, 21, 44, 50, 56, 61	V <sub>DD</sub>	Power	3.3V Power Sup	3.3V Power Supply			
1, 16, 26, 27, 30, 36, 37, 38, 39, 40, 41, 53, 62, 63, 72	GND	Power	Ground.				
57	ŌĒ	Input	Output enable (Active LOW). When HIGH, all outputs are Hi-Z and chip is placed into Standby Mode. Under Standby Mode, the current supply is from VDD50.				



# **BLOCK DIAGRAM EXPLANATION**

# **DDC Switch Block**

Passive NMOS based 3:1 mux for DDC channels from each HDMI/DVI input connector. This section can remain active even when 3.3V supply is gone, as long as 5.0V from TMDS connector is connects to the PI3HDMI1310-A IC.

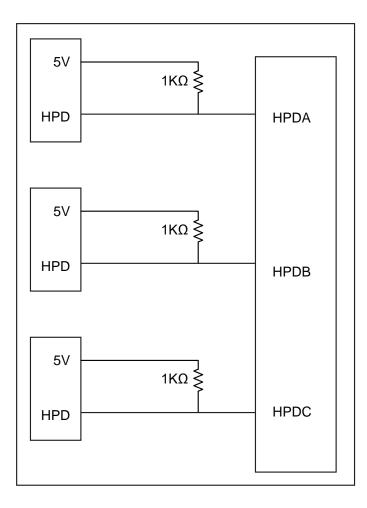
### **3:1 High speed Differential Channel Block**

4-differential channels per port. 3 channels are targeted for high speed data channels (250Mbps to 3.4Gbps) and 1 channel is targeted for high speed clock signal (25MHz to 340MHz).

## HPD Control Channels Block

Drives each HPD channels through the input pin, HPD\_Sink.

This signal will need to drive external pull-down transistor circuit before connecting to the HDMI/DVI connector. The external pull down circuit will look like the following:





### Truth table for HPDx signals

	Control Pins			Hot	Plug Detect Sta	atus
ŌĒ	SEL1	SEL2	HPD_Sink	HPD A	HPD B	HPD C
x	L	L	L	Hi-Z	Hi-Z	Hi-Z
x	L	L	H	L	Hi-Z	Hi-Z
X	L	H	L	Hi-Z	Hi-Z	Hi-Z
X	L	H	H	Hi-Z	L	Hi-Z
X	H	L	L	Hi-Z	Hi-Z	Hi-Z
X	H	L	H	Hi-Z	Hi-Z	L
X	H	H	L	Hi-Z	Hi-Z	Hi-Z
X	H	H	H	Hi-Z	Hi-Z	Hi-Z

\*All Hi-Z will become H if external pull-up connected at the output.

### **Maximum Ratings**

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	65°C to +150°C
Supply Voltage to Ground Potential	0.5V to +3.6V
DC Input Voltage	-0.5V to 3.6V
DC Output Current	120mA
Power Dissipation	0.5W

**Note:** Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

# **DC Electrical Characteristics for Switching over Operating Range** ( $T_A = -40^{\circ}C$ to $+85^{\circ}C$ , $V_{DD} = 3.3V \pm 10\%$ )

Parameter	Description	Test Conditions <sup>(1)</sup>	Min	Typ <sup>(2)</sup>	Max	Units
V <sub>IH</sub>	Input HIGH Voltage	Guaranteed HIGH level	1.5			
VIL	Input LOW Voltage	Guaranteed LOW level	-0.5		0.65	V
V <sub>IK</sub> (1)	Clamp Diode Voltage	$V_{DD} = Max., I_{IN} = -18mA$		-0.7	-1.2	
IIH	Input HIGH Current	$V_{DD} = Max., V_{IN} = V_{DD}$			±5	
IIL	Input LOW Current	$V_{DD} = Max., V_{IN} = GND$			±5	μΑ
I <sub>OFF</sub>	Off Leakage Current	$V_{DD} = 0V$			10	
Status Pins (H	IPD_SINK)					
V <sub>IH</sub>	LVTTL Input HIGH Voltage		2		5.3	N
VIL	LVTTL Input LOW Voltage		GND		0.8	V
Rp	Pull-down Resistance	$V_{DD}50 = 5.0V$		100K		Ohm

1. Substrate diode voltage drop. For testing reference.



# **Power Supply Characteristics**

Parameters	Description	Test Conditions <sup>(1)</sup>	Min.	<b>Typ.</b> <sup>(2)</sup>	Max.	Units
I <sub>DD</sub>	Operating Power Supply Current	$V_{DD} = Max., V_{SELx} = GND \text{ or}$ $V_{DD}$		6	10	mA
I <sub>DDQ</sub>	Standby Supply Current	OE - High		3	5	

**Dynamic Electrical Characteristics Over the Operating Range** (T<sub>A</sub>= -40° to +85°C, V<sub>DD</sub> = 3.3V ±10%, GND=0V)

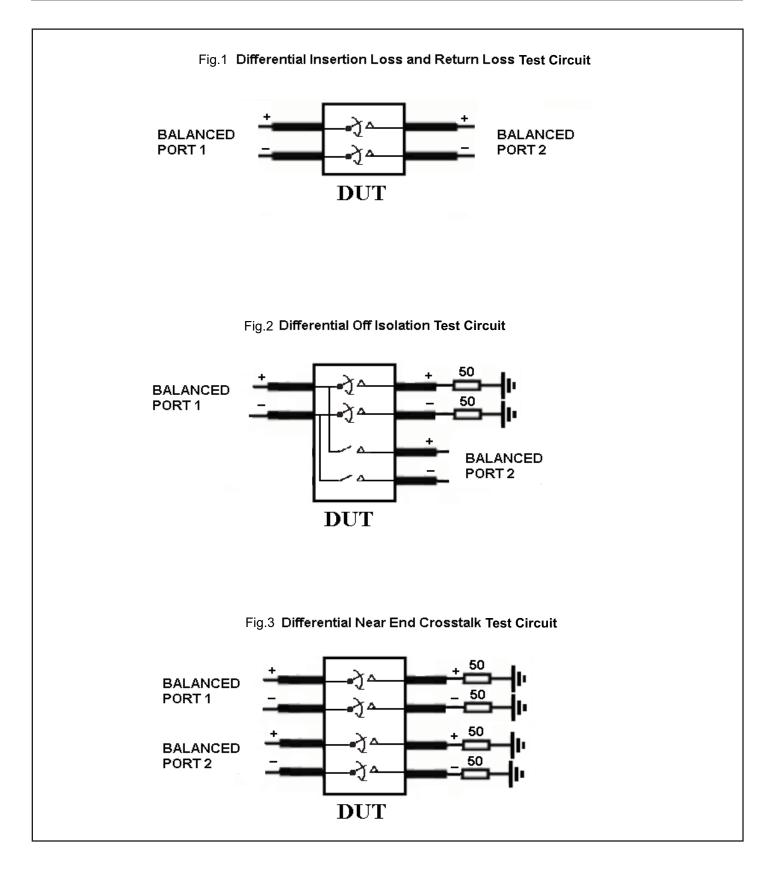
Parameter	Description	Test Conditions		Min	Typ. <sup>(2)</sup>	Max	Units
		See Fig. 3 for f= 1.13 GHz			-34		
X <sub>TALK</sub>	Crosstalk on High Speed Channels	Measurement Setup	f = 825 MHz		-36		
	OFF Isolation on High Speed	See Fig. 2 for	f= 1.13 GHz		-28		dB
	Channels	Measurement Setup	f = 825 MHz		-32		
I <sub>LOSS</sub>	Differential Insertion Loss on High Speed Channels (see figure 1)	DR = 1.54Gbps $DR = 2.0Gbps$ $DR = 2.25Gbps$ $DR = 3.0Gbps$ $DR = 3.4Gbps$			-1.5 -1.73 -1.82 -1.99 -2.08		dB
BW	-3dB BW for TMDS channels				3.0		GHz
Status Pins	Status Pins (HPD) - open drain output buffer						
V <sub>OL(TTL)</sub>	TTL Low-level output voltage	$I_{OL} = 4mA$				0.4	V

Notes:

1. For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at  $V_{DD} = 3.3V$ ,  $T_A = 25^{\circ}C$  ambient and maximum loading.



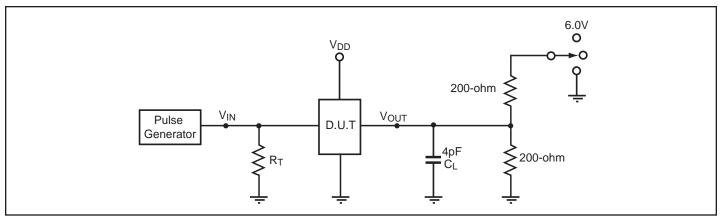




Parameter	Description	Min.	Max.	Units	
tpZH, tpZL	Line Enable Time	0.5	25		
tpHZ, tPLZ	Line Disable Time	0.5	25	ns	
tb-b	Bit-to-bit skew within the same differential pair 15		15	ng	
t <sub>ch-ch</sub>	Channel-to-channel skew		35	ps	

### Switching Characteristics ( $T_A = -40^\circ$ to $+85^\circ$ C, $V_{DD} = 3.3V \pm 10\%$ )

# **Test Circuit for Electrical Characteristics**<sup>(1-5)</sup>



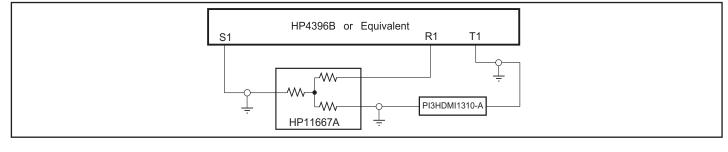
#### Notes:

- 1.  $C_L$  = Load capacitance: includes jig and probe capacitance.
- 2.  $R_T$  = Termination resistance: should be equal to  $Z_{OUT}$  of the Pulse Generator
- 3. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
- output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- 4. All input impulses are supplied by generators having the following characteristics:  $PRR \le MHz$ ,  $Z_0 = 50\Omega$ ,  $t_R \le 2.5ns$ ,  $t_F \le 2.5ns$ .
- 5. The outputs are measured one at a time with one transition per measurement.

### **Switch Positions**

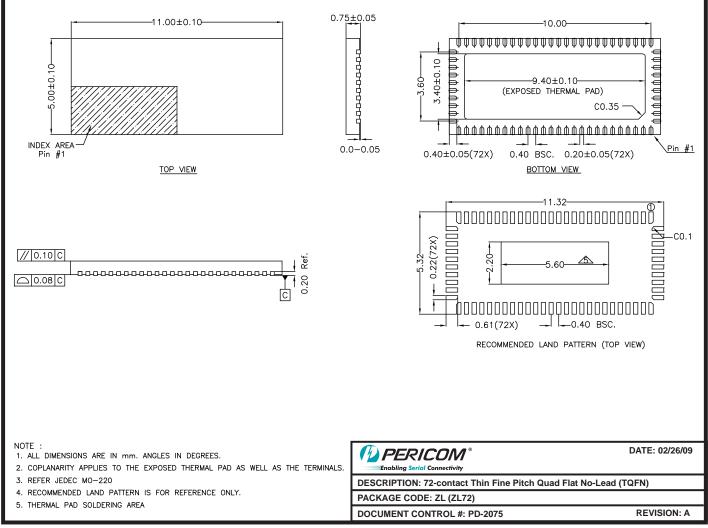
Test	Switch
t <sub>PLZ</sub> , t <sub>PZL</sub> (output on B-side)	6.0V
t <sub>PHZ</sub> , t <sub>PZH</sub> (output on B-side)	GND
Prop Delay	Open

# **Test Circuit for Dynamic Electrical Characteristics**





# Packaging Mechanical: 72-Contact TQFN



09-0134

Note:

· For latest package info, please check: http://www.pericom.com/products/packaging/mechanicals.php

### **Ordering Information**

Ordering Code	Package Code	Package Description
PI3HDMI1310-AZLE	ZL	Pb-free and Green 72-contact TQFN

#### Notes:

· Thermal characteristics can be found on the company web site at www.pericom.com/packaging/

• "E" denotes Pb-free and Green

• Adding an "X" at the end of the ordering code denotes tape and reel packaging